

A S S I G N M E N T

**United States (Sole or Joint)
(Excluding Foreign Rights)**

09/237618

WHEREAS, I/We, Mikuni AMO

residing at c/o Kitano Engineering Co., Ltd.,
98-1, Aza-tsukinowa Tanocho, Komatsushima-shi,
Tokushima-ken 773-0008, Japan

have invented certain new and useful improvements in METHOD OF AND APPARATUS FOR
LAMINATING DISC-SHAPED SUBSTRATES
for which an application for United States Letters Patent was signed on even date.

WHEREAS, Kitano Engineering Co., Ltd.

having a place of business at 98-1, Aza-tsukinowa Tanocho, Komatsushima-shi,
Tokushima-ken 773-0008, Japan

hereinafter called the "Assignee", is desirous of acquiring the entire right, title and
interest in and to said invention and in and to any Letters Patent that may be granted
therefor, in the United States and its territorial possessions.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) and other
valuable considerations, the receipt whereof is hereby acknowledged, I/we have sold,
assigned and transferred, and by these presents do sell, assign, transfer and confirm in
and to said Assignee my/our full and exclusive right to the said invention in the United
States and its territorial possessions and my/our entire right, title and interest in and to
said application and any and all Letters Patent which may be granted therefor in the
United States and its territorial possessions and in and to any and all divisions, reissues,
continuations and extensions thereof.

I/We hereby authorize and request the Patent Office Officials in the United States to
issue any and all of said Letters Patent, when granted, to said Assignee for the sole use
and behoof of the said Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I/we have hereunto set my/our hand(s).

Witnessed by:

Shinji Shirasaki
Shinji SHIRASAKI

Inventor(s):

Mikuni Amo
Mikuni AMO

Date: January 20,
1999